Monday, September 26			3:00-17:30 nort Course A (201) : Scaling an	nd monolithic vs. heterogeneous	integration for advanced futur	e technology nodes				
				vances in ultra-wide-bandgap se		re technology nodes				
esday, September 27				5 1						
			9:00-11:	10 (Convention Hall) : Opening &	& Award Ceremony & Plenary	Session 1				
101	102	103	104	105	201	301	302	303	304	
		11:30 ~ 12:15	11:30 ~ 12:30	11:30 ~ 12:45	11:30 ~ 12:30	11:30 ~ 12:45	11:30 ~ 12:30	11:30 ~ 12:30	11:30 ~ 12:30	
		[C-1] Energy Harvesting Devices	[D-1] Micro/Nano Technologies for Biosensing and Interfaces	[E-1] Emerging Thin Film Devices and Technologies	[F-1] Ferroelectric Memory Materials	[G-1] Cryo-CMOS	[H-1] Characterization I: Low Dimensional Devices and Materials	[J-1] Advanced Technologies for GaN Devices	[K-1] 3D Integration and Adva Packaging I	
				Lunch						
14:00 ~ 15:30	14:00 ~ 15:45	14:00 ~ 15:30	14:00 ~ 15:45	14:00 ~ 16:00	14:00 ~ 15:30	14:00 ~ 16:00	14:00 ~ 15:45	14:00 ~ 15:30	14:00 ~ 15:15	
2] New Materials and Platforms for Photonics	[B-2] Wide Bandgap Materials	[C-2] Inorganic Semiconductor Materials & Applications	[D-2] Biosensor, Chips and Microfluidic Devices for Cell Functions	Devices and Technologies	[F-2] PCM, MRAM, and RRAM	[G-2] Modeling, Simulation and Characterization	[H-2] Novel Function Devices	[J-2] GaN-based High-speed Devices	[K-2] Advanced Sensor Syste	
	16:15 ~ 18:00	16:15 ~ 18:00	16:15 ~ 18:00	16:15 ~ 18:00	16:15 ~ 18:00	16:15 ~ 17:45 Area1&2&9	16:15 ~ 18:00	16:15 ~ 17:45	16:15 ~ 17:45 Area3&5&12	
	[B-3] Group IV Materials I	[C-3] Perovskite Solar Cells	[D-3] Advanced Technologies for Bio- and Chemical Sensing	[E-3] Oxide Semiconductor TFT	[F-3] Ferroelectric Devices	[G-3] Quantum Computing I Focus Session 1	[H-3] Characterization II: Low Dimensional Devices and Materials	[J-3] High-speed Devices	[K-3] Design, Process, and Techr for High-performance Chiple Focus Session 3	
			18:30	0-20:30 (Convention Hall) : Comp		Event		•		
ednesday, September 28										
101	102	103	104	105 09:00 ~ 11:15	201	301 09:00 ~ 10:15	302	303	304	
		09:00 ~ 10:15		Area1&10	09:00 ~ 10:15	Area1&2&9	09:00 ~ 10:00	09:00 ~ 10:15	09:00 ~ 10:15	
		[C-4] Battery, Photocatalyst, Photodetector		[E-4] Oxide Semiconductors for Logic and Memory Applications Joint Session	[F-4] Emerging Memory Devices	[G-4] Quantum Computing II Focus Session 1	[H-4] Device Application I: Low Dimensional Devices and Materials	[J-4] Ultrawide Bandgap Semiconductor Devices	[K-4] Design, Process, and Tech for High-performance Chiplet Integration and Advanced Packa	
10:45 ~ 12:15	10:45 ~ 12:00	10:45 ~ 12:00	10:45 ~ 12:15	Bro	10:45 ~ 12:00	10:45 ~ 12:15	10:45 ~ 11:45	10:45 ~ 12:00	10:45 ~ 12:00	
	ID 51 Advanced Metable	Area1&2&9	[D-5] Transistor Technologies for				III 51 Device Application III I am	II 51 C.C Danassass and		
[A-5] UV Sources and Detectors	[B-5] Advanced Materials, Nanofabrication and Thin Films I	[C-5] Quantum Computing III Focus Session 1	Biological and Electrochemical Applications	Lunch	[F-5] 3D NAND Flash Memory	[G-5] Image Sensor Technology	[H-5] Device Application II: Low Dimensional Devices and Materials	[J-5] SiC Processes and Characterizations	[K-5] Advanced Neuron and AI S	
13:30 ~ 15:45	13:30 ~ 15:15	13:30 ~ 15:30 Area1&2&9	13:30 ~ 15:30	13:30 ~ 15:30	13:30 ~ 15:00	13:30 ~ 15:15 Area1&2	13:30 ~ 15:00	13:30 ~ 15:45	13:30 ~ 15:30	
[A-6] III-V Light Sources	[B-6] Advanced Materials, Nanofabrication and Thin Films II	[C-6] Quantum Computing IV Focus Session 1	[D-6] Functional Devices and Application	[E-6] Advanced Oxide Sensors	[F-6] Charge-Based Memory Devices for AI Applications	[G-6] Ferroelectric Devices Joint Session	[H-6] Growth and Synthesis: Low Dimensional Devices and Materials	[J-6] Interface Technologies	[K-6] MEMS and Advance Metallization I	
				16:00-17:30 (Convention						
				18:00-20:00 (Convention Hall) :						
ursday, September 29										
101	102	103	104	105	201	301	302	303	304	
				9:00 ~ 10:45	09:00 ~ 10:15	09:00 ~ 10:15			09:00 ~ 10:15	
				[E-7] MEMS and Advanced Metallization II	[F-7] In-Memory and Unconventional Computing	[G-7] Advanced CMOS: Device Technology			[K-7] Advanced Systems w Innovative Devices	
	10:45 ~ 12:00	10:45 ~ 12:00	10:45 ~ 12:00	Bro	10:45 ~ 12:00	10:45 ~ 11:45	10:45 ~ 12:00	10:45 ~ 12:00	10:45 ~ 12:00	
					TO IN DOI ON				Area1&12 [K-8] Innovative Devices and Sy	
	[B-8] Group IV Materials II	[C-8] Spintronics I	[D-8] Optoelectronics and Thermoelectronic Devices	Lunch	[F-8] Memory Devices for New Applications	[G-8] Ferroelectric Material and Process	[H-8] Device Application III: Low Dimensional Devices and Materials	[J-8] Si and SiC Power Devices	for Advanced Imaging and Ser Joint Session	
13:30 ~ 15:15		13:30 ~ 15:30			13:30 ~ 15:15 Area1&2&8			13:30 ~ 15:00	13:30 ~ 15:15	
A-9] Imaging Sensors and Detectors		[C-9] Thermoelectric Devices			[F-9] CMOS and Memory Applications of Low Dimensional Materials I Focus Session 2			[J-9] GaN Power Devices	[K-9] Advanced Device-based C and Power Management Syste	
16:00 ~ 18:00		16:00 ~ 17:30		Bro	eak 16:00 ~ 17:45 Area1&2&8	16:00 ~ 18:00		16:00 ~ 17:45		
A-10] Integrated Photonic Devices		[C-10] Spintronics II			[F-10] CMOS and Memory Applications of Low Dimensional Materials II Focus Session 2	[G-10] Advanced CMOS: Device, Process and Material		[J-10] DRAM, SRAM, and 3D NAND		
Area Scope		Area 1: Advanced CMOS: Material S	Science / Process Engineering / Device	Technology	Area Scope		Area 7: Organic / Molecular / Bio-ele	ectronics	•	
	Area 2: Advanced and Emerging Memories / New Applications					Area 8: Low Dimensional Devices and Materials				
Area 3: Interconnect / 3D Integrations / MEMS Area 4: Power / High-speed Devices and Materials							Area 9: Novel Functional / Quantum / Spintronic Devices and Materials Area 10: Thin Film Electronics: Oxide / Non-single Crystalline / Novel Process			
		Area 5: Photonics: Devices / Integration / Related Technology					Area 11: Advanced Materials: Synthesis / Crystal Growth / Characterization			
		Area 5: Photonics: Devices / Integrat	ion / Related Technology				Area 11: Advanced Materials: Synthe	esis / Crystal Growth / Characterization		